

N-Channel Logic Level Enhancement Mode Power MOSFET

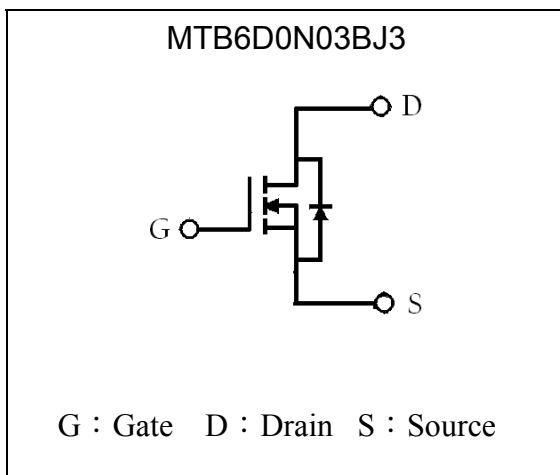
MTB6D0N03BJ3

Features

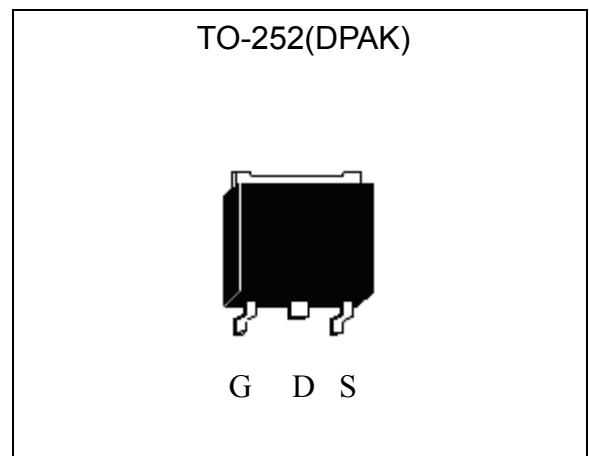
- Single Drive Requirement
- Low On-resistance
- Fast Switching Characteristic
- Repetitive Avalanche Rated
- Pb-free lead plating and halogen-free package

BV_{DSS}		30V
$I_D @ V_{GS}=10V, T_A=25^\circ C$		12A
$I_D @ V_{GS}=10V, T_C=25^\circ C$		44A
$R_{DS(on)(TYP)}$	$V_{GS}=10V, I_D=25A$	$6.4m\Omega$
	$V_{GS}=4.5V, I_D=15A$	$10.4m\Omega$

Equivalent Circuit

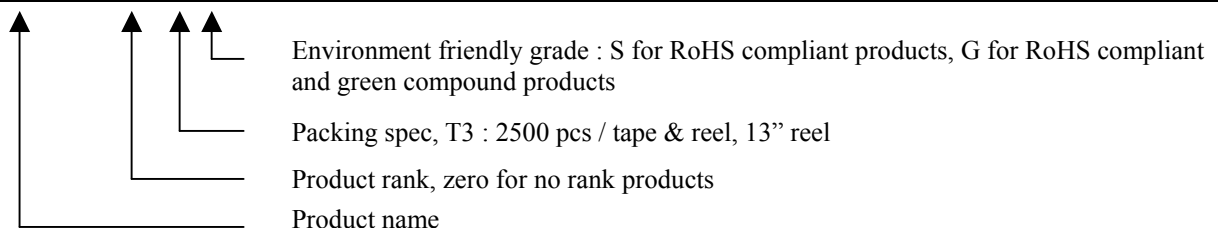


Outline



Ordering Information

Device	Package	Shipping
MTB6D0N03BJ3-0-T3-G	TO-252 (Pb-free lead plating and halogen-free package)	2500 pcs / tape& reel



**Absolute Maximum Ratings** (Ta=25°C, unless otherwise specified)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V _{DS}	30	V
Gate-Source Voltage		V _{GS}	±20	
Continuous Drain Current @ V _{GS} =10V, T _C =25°C		I _D	44	A
Continuous Drain Current @ V _{GS} =10V, T _C =100°C			28	
Continuous Drain Current @ V _{GS} =10V, T _A =25°C			12	
Continuous Drain Current @ V _{GS} =10V, T _A =70°C			9.6	
Pulsed Drain Current		I _{DM}	176 *1	
Avalanche Energy @ L=0.1mH, I _D =30A, V _{DD} =15V		E _{AS}	45 *3	mJ
Repetitive Avalanche Energy @ L=0.05mH		E _{AR}	3.3	
Total Power Dissipation	T _C =25°C	P _D	33	W
	T _C =100°C		13.2	
	T _A =25°C	P _{DSM}	2.5 *2	
	T _A =70°C		1.6 *2	
Operating Junction and Storage Temperature Range		T _j , T _{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R _{th,j-c}	3.8	°C/W
Thermal Resistance, Junction-to-ambient, max	R _{th,j-a}	50 *2	

Note : 1. Pulse width limited by maximum junction temperature.

2. Surface mounted on a 1 in² pad of 2oz copper. In practice R_{th,j-a} will be determined by customer's PCB characteristics.
125°C/W when mounted on a minimum pad of 2 oz. copper.3. 100% tested by conditions of L=0.1mH, I_{AS}=10A, V_{GS}=10V, V_{DD}=15V, rated 30V**Characteristics (T_C=25°C, unless otherwise specified)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	30	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	1	-	2.5		V _{DS} = V _{GS} , I _D =250μA
G _{FS} *1	-	25	-	S	V _{DS} =5V, I _D =15A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V
I _{DSS}	-	-	1	μA	V _{DS} =24V, V _{GS} =0V
	-	-	10		V _{DS} =24V, V _{GS} =0V, T _j =85°C
R _{DS(ON)} *1	-	6.4	9	mΩ	V _{GS} =10V, I _D =25A
	-	10.4	15		V _{GS} =4.5V, I _D =15A
Dynamic					
C _{iss}	-	733	-	pF	V _{DS} =15V, V _{GS} =0V, f=1MHz
C _{oss}	-	167	-		
C _{rss}	-	85	-		
Q _g *1, 2	-	14.8	-	nC	V _{DS} =15V, V _{GS} =10V, I _D =14A
Q _{gs} *1, 2	-	2.9	-		
Q _{gd} *1, 2	-	3.1	-		

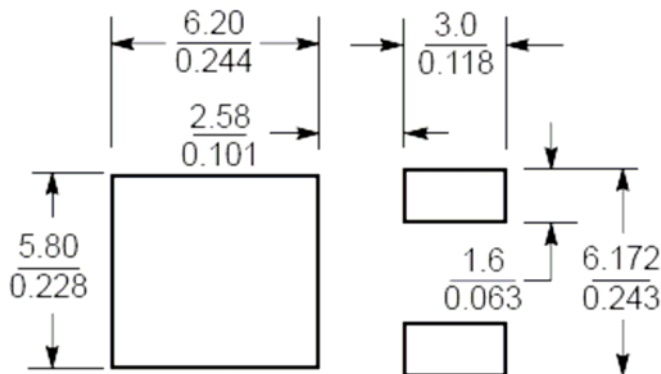
Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
t _d (ON) *1, 2	-	8.8	-	ns	V _{DS} =15V, I _D =14A, V _{GS} =10V, R _{GS} =3 Ω
t _r *1, 2	-	14.6	-		
t _d (OFF) *1, 2	-	25	-		
t _f *1, 2	-	6.4	-		
R _g	-	1.9	-	Ω	f=1MHz
Source-Drain Diode					
I _S *1	-	-	44	A	
I _{SM} *3	-	-	176		
V _{SD} *1	-	0.87	1.3	V	I _S =25A, V _{GS} =0V
t _{rr}	-	10.5	-	ns	I _F =14A, dI _F /dt=100A/μs
Q _{rr}	-	4.3	-	nC	

Note : *1.Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

*2.Independent of operating temperature

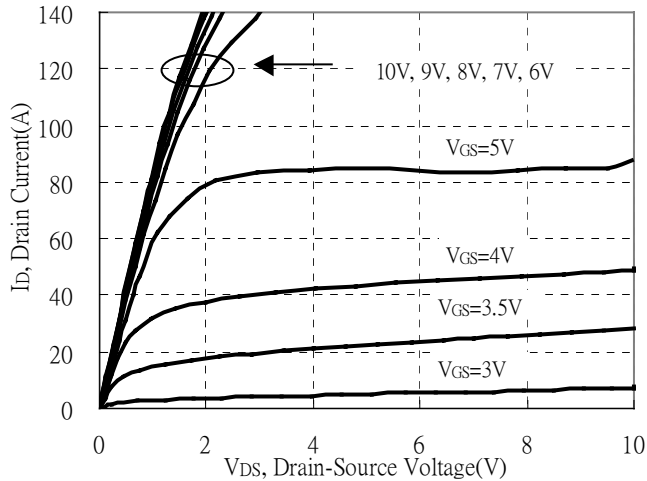
*3.Pulse width limited by maximum junction temperature.

Recommended soldering footprint


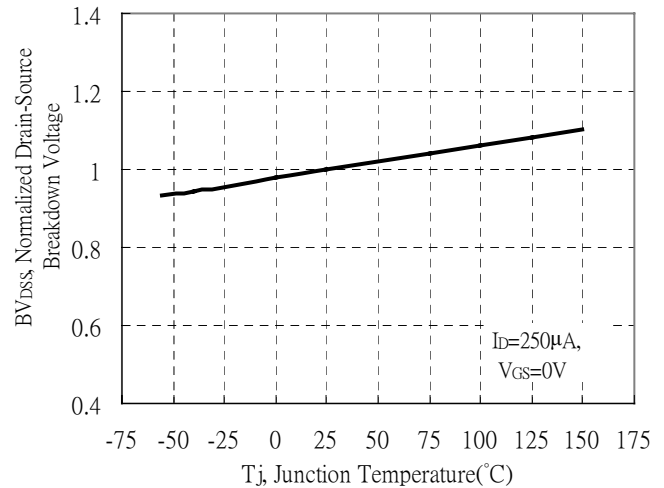
Unit ($\frac{\text{mm}}{\text{inch}}$)

Typical Characteristics

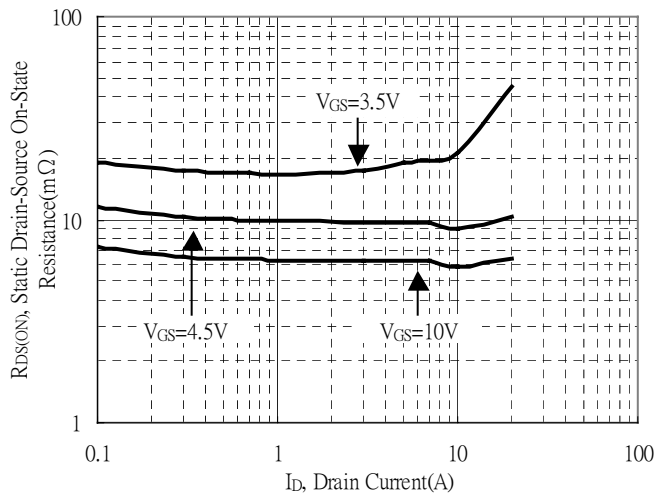
Typical Output Characteristics



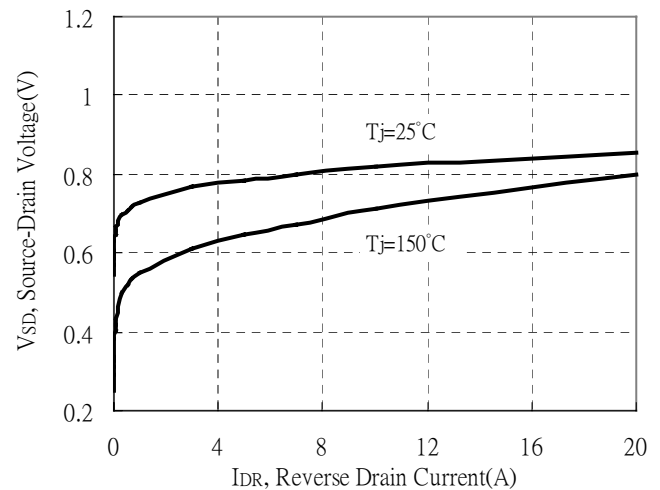
Breakdown Voltage vs Ambient Temperature



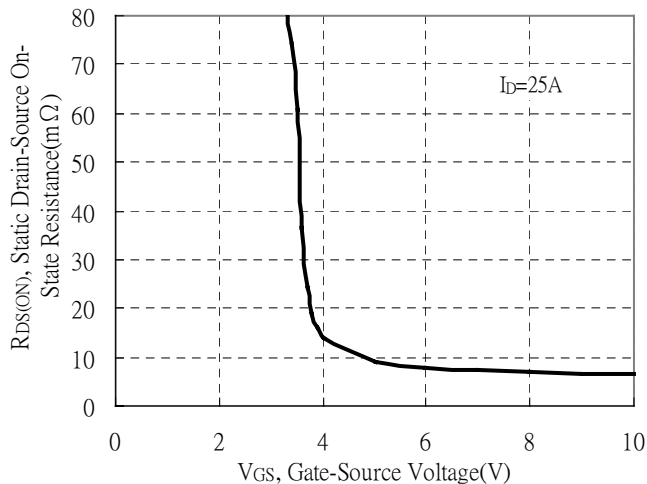
Static Drain-Source On-State resistance vs Drain Current



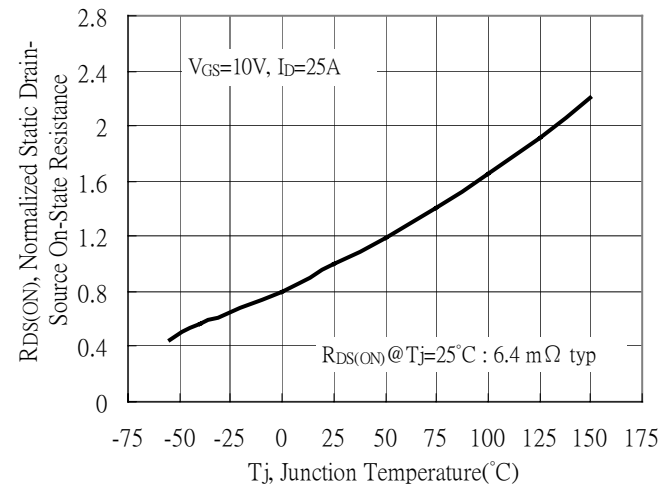
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage



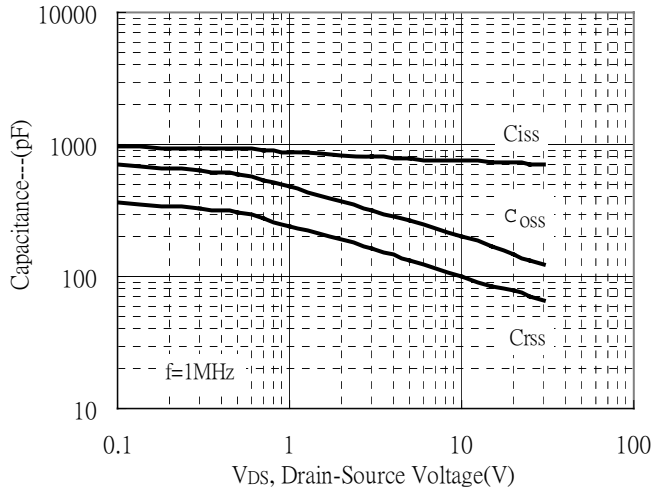
Drain-Source On-State Resistance vs Junction Temperature



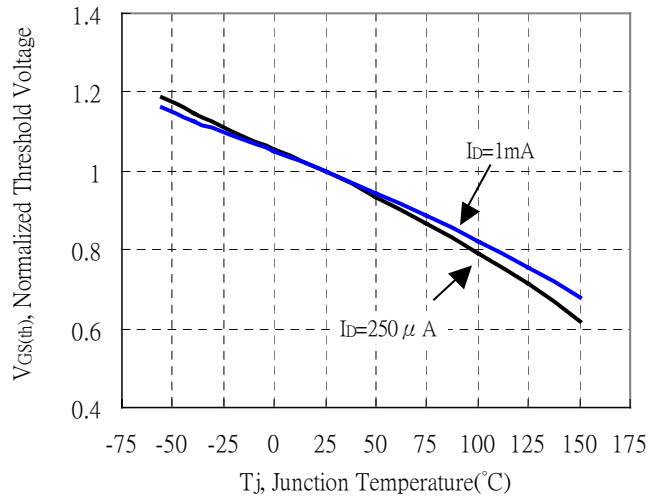


Typical Characteristics(Cont.)

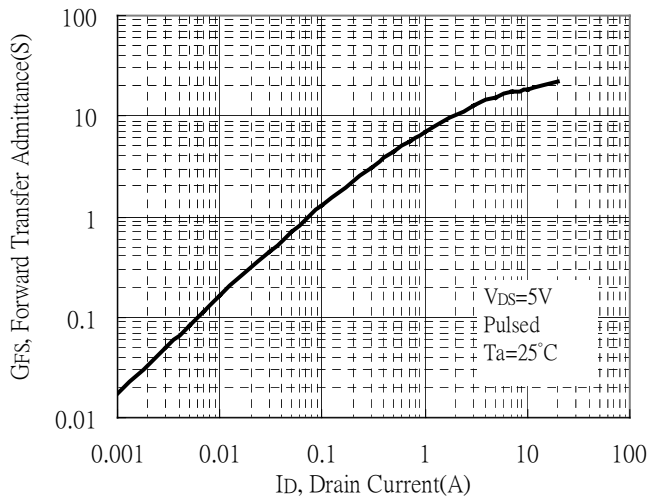
Capacitance vs Drain-to-Source Voltage



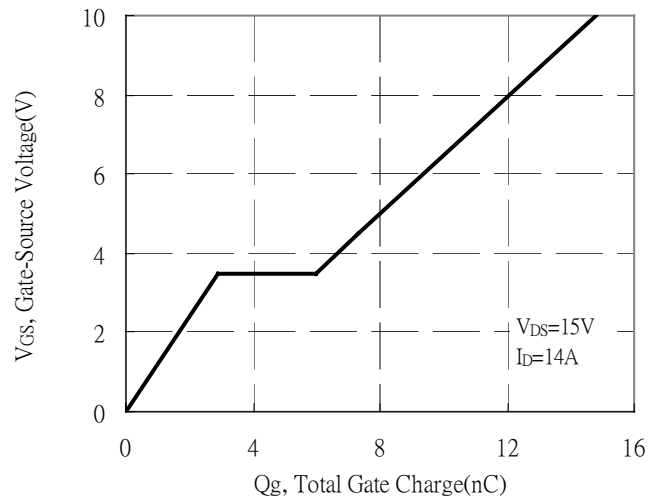
Threshold Voltage vs Junction Temperature



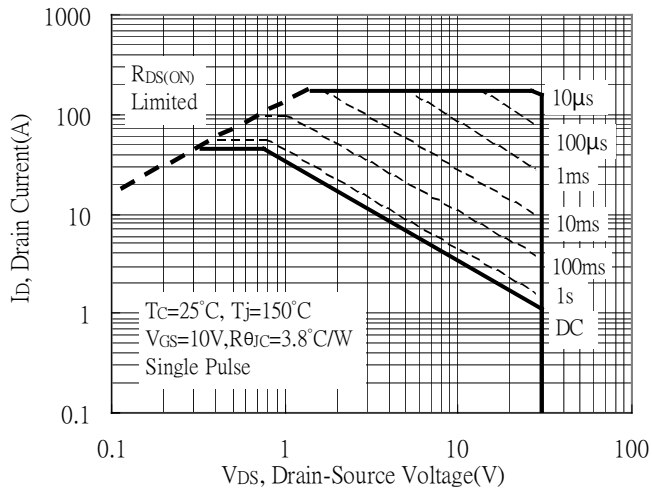
Forward Transfer Admittance vs Drain Current



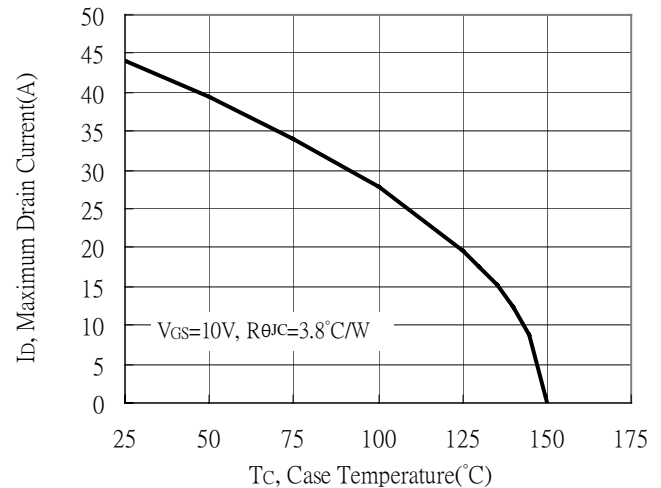
Gate Charge Characteristics



Maximum Safe Operating Area

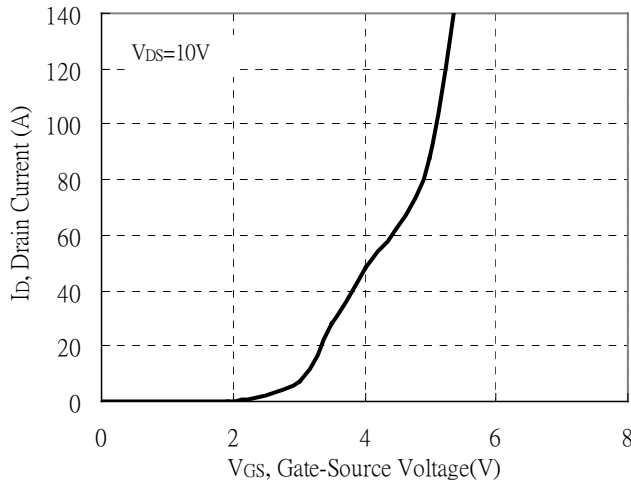


Maximum Drain Current vs Case Temperature

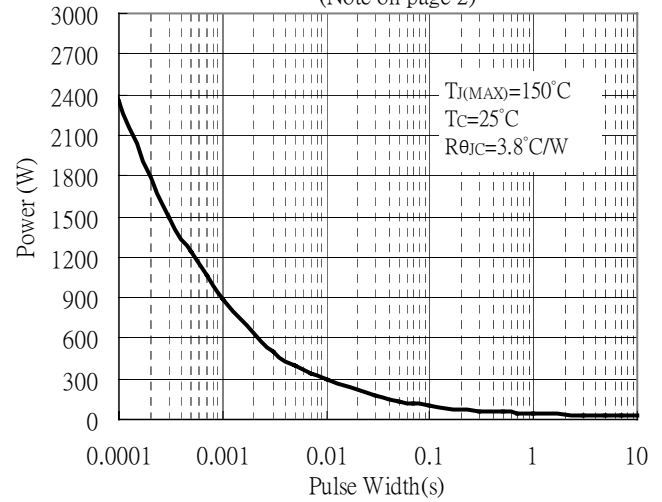


Typical Characteristics(Cont.)

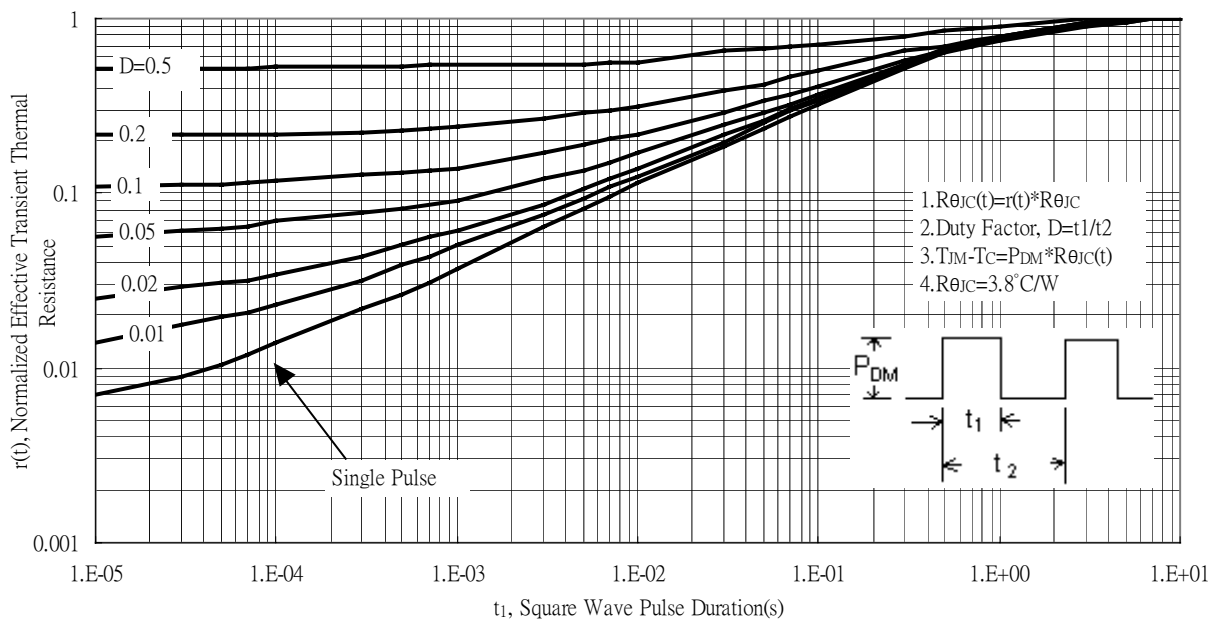
Typical Transfer Characteristics



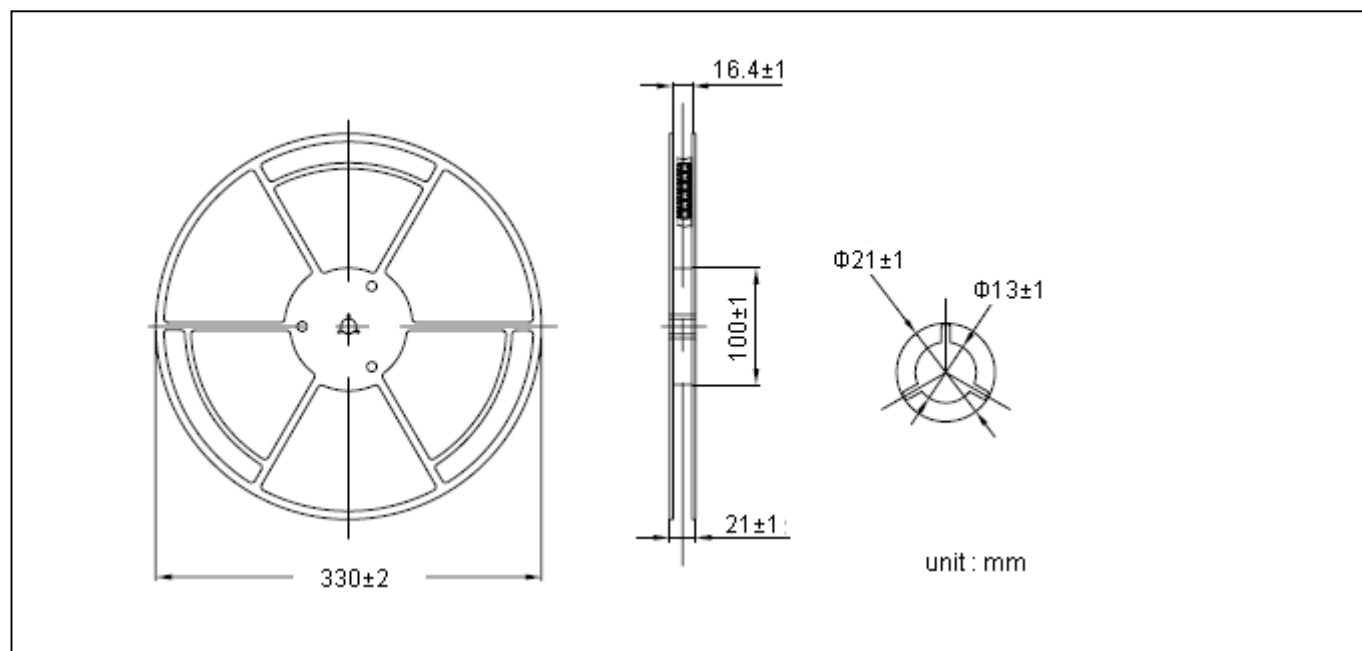
Single Pulse Power Rating, Junction to Ambient
(Note on page 2)



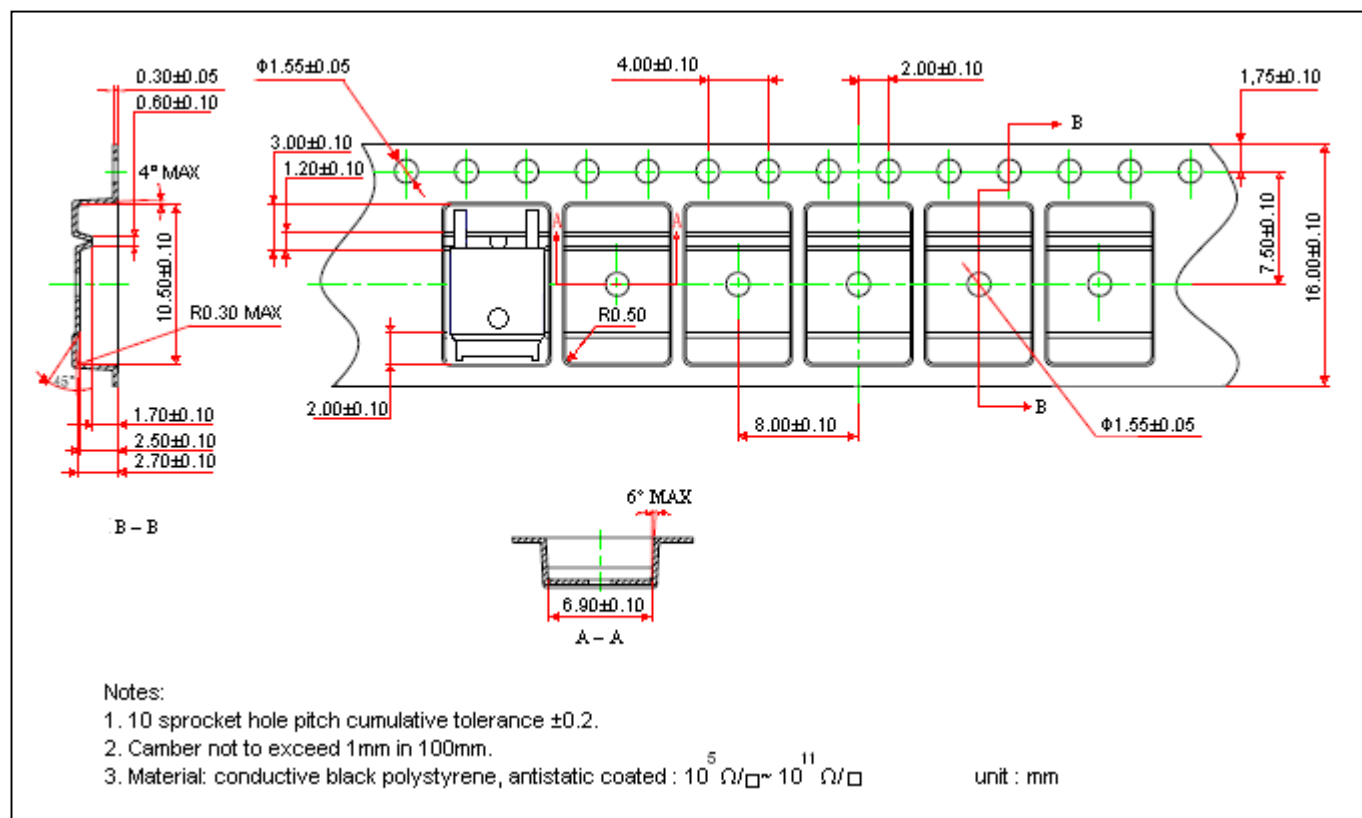
Transient Thermal Response Curves



Reel Dimension



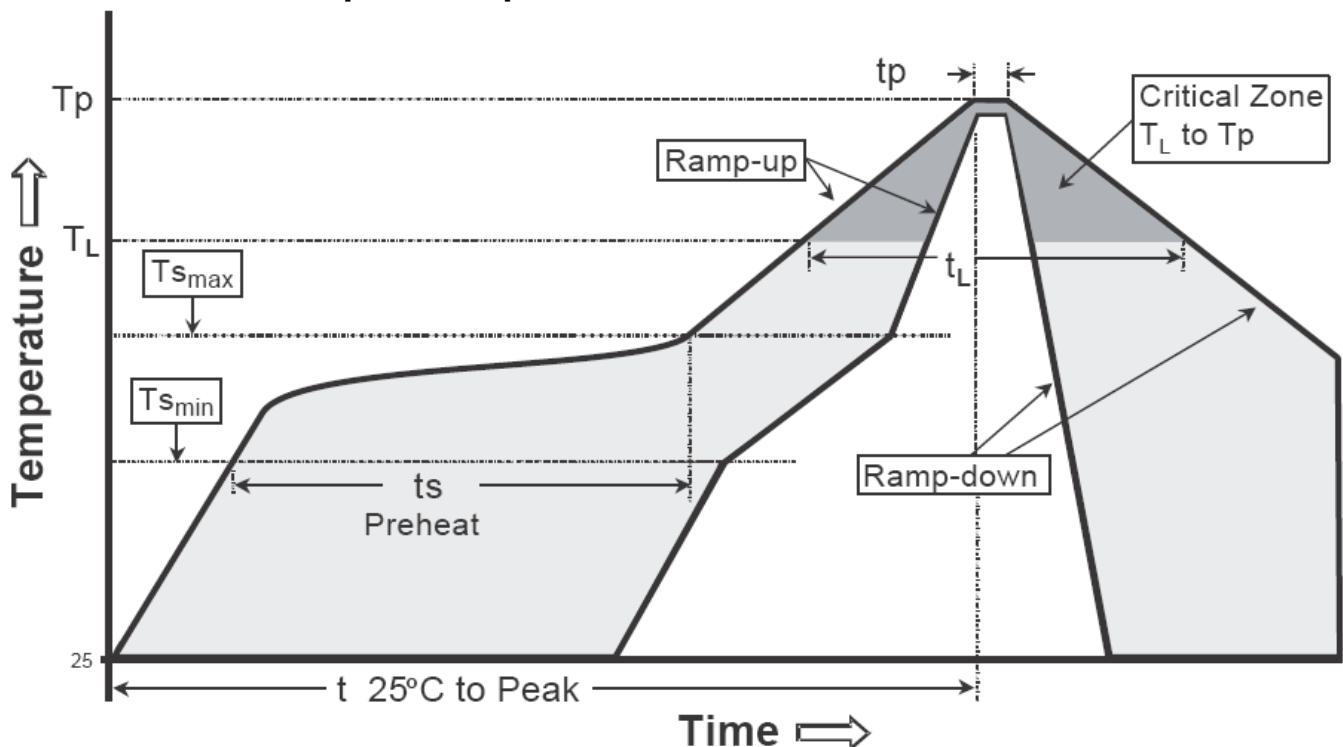
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

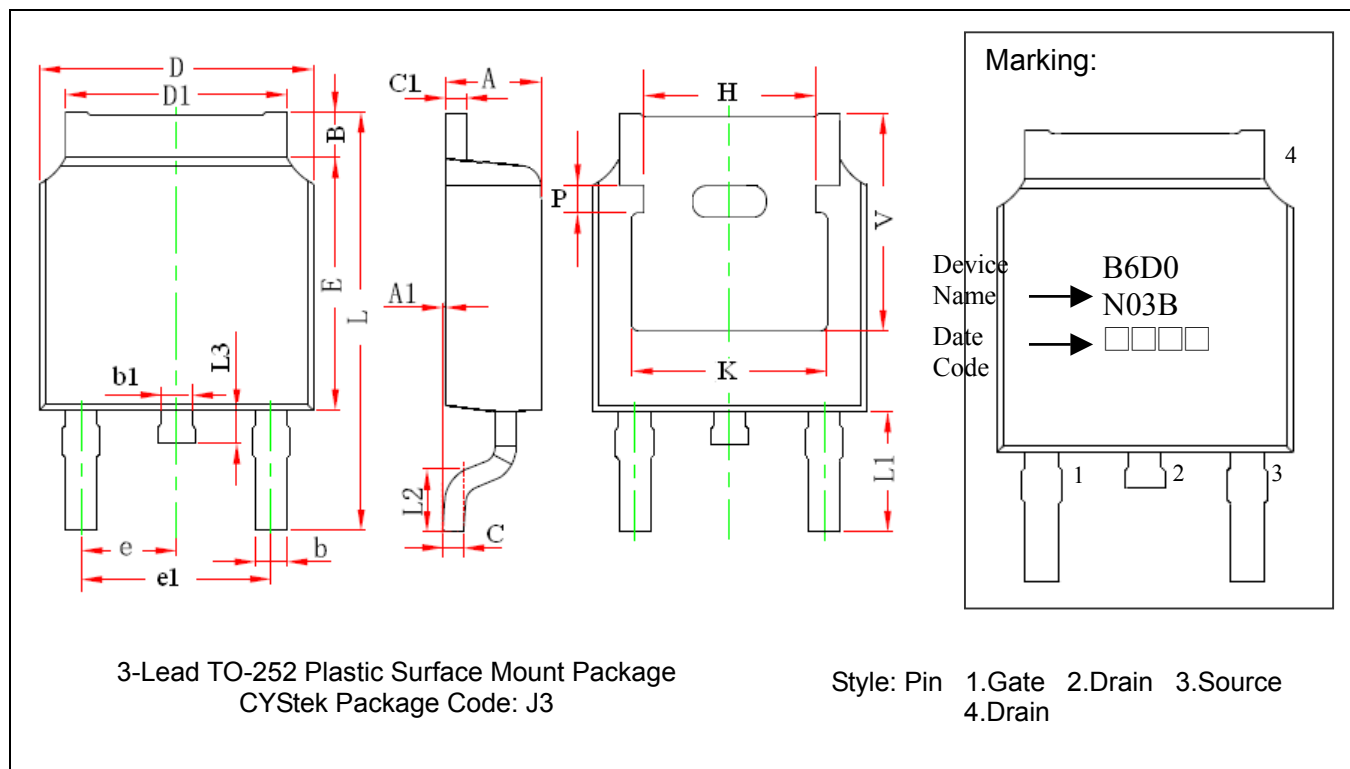
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-252 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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